Silicon N-Channel MOS FET

HITACHI

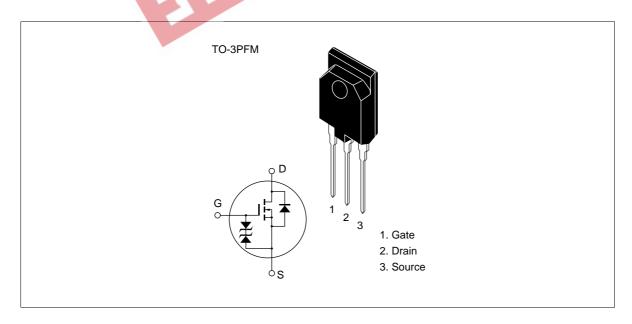
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Tom.cn Suitable for switching regulator and DC-DC converter

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item		Symbol	Ratings	Unit	
Drain to source voltage	2SK1328	V _{DSS}	450	V	
	2SK1329		500		
Gate to source voltage	V_{GSS}	±30	V		
Drain current		I _D	12	Α	
Drain peak current		l _{D(pulse)} *1	48	Α	
Body to drain diode reverse of	drain current	I _{DR}	12	А	
Channel dissipation		Pch*2	60	W	
Channel temperature		Tch	150	°C	
Storage temperature		Tstg	-55 to +150	°C	
		N.S.	-55 (0 +150		

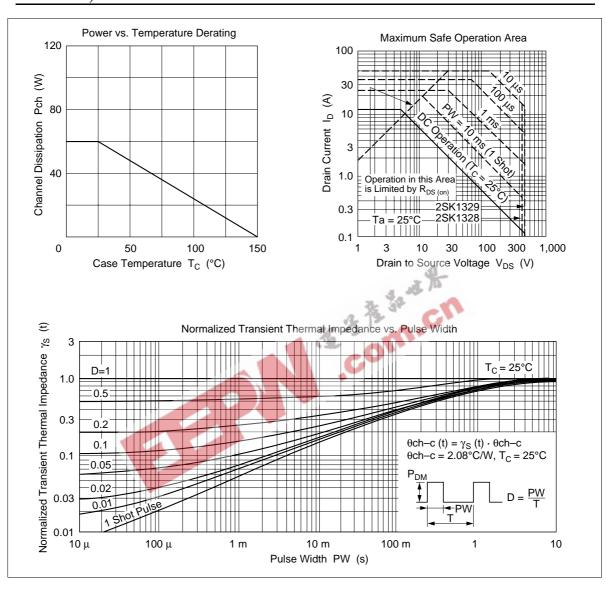


Electrical Characteristics (Ta = 25°C)

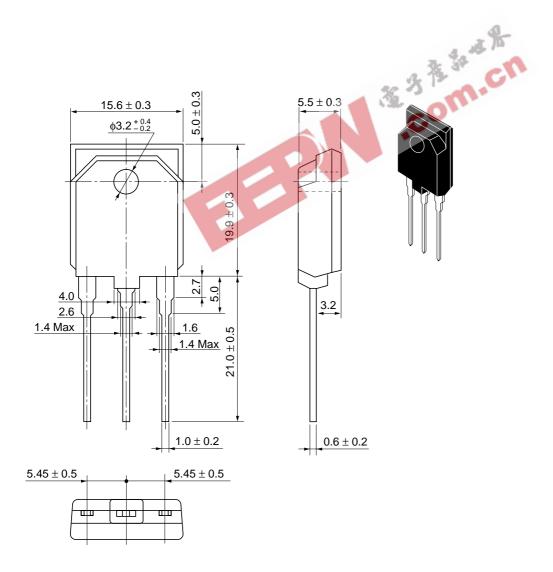
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1328	$V_{(BR)DSS}$	450	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
breakdown voltage	2SK1329	-	500	-			
Gate to source breakd voltage	down	$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak c	urrent	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage	2SK1328	I _{DSS}	_	_	250	μΑ	$V_{DS} = 360 \text{ V}, V_{GS} = 0$
drain current	2SK1329	-					$V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source cutoff	voltage	$V_{\rm GS(off)}$	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static Drain to source	2SK1328	R _{DS(on)}	_	0.40	0.55	Ω	$I_D = 6 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
on state resistance	2SK1329	-	_	0.45	0.60	ک	
Forward transfer adm	ittance	yfs	6.0	10	_	S	$I_D = 6 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance		Ciss	_	1450	- 為	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance		Coss	_	410 🦋	3"	pF	f = 1 MHz
Reverse transfer capa	acitance	Crss	- \	55	7.0	pF	-
Turn-on delay time		t _{d(on)}	± 10	20		ns	$I_D = 6 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time		t _r	<i>-), </i>	70		ns	$R_L = 5 \Omega$
Turn-off delay time		t _{d(off)}		120	_	ns	-
Fall time	1	t _f	_	60	_	ns	-
Body to drain diode for voltage	orward	V _{DF}	_	1.0	_	V	$I_F = 12 \text{ A}, V_{GS} = 0$
Body to drain diode re recovery time	everse	t _{rr}	_	450	_	ns	$I_F = 12 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note: 1. Pulse test

See characteristic curves of 2SK1165, 2SK1166.



Unit: mm



Hitachi Code	TO-3PFM		
JEDEC	_		
EIAJ	_		
Weight (reference value)	5.6 g		

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